## STMP3770XXBJEA2N

(Not Recommended for New Designs)

## PMP CONTROLLER

#### Package

Buy Options Operating Characteristics Environmental Information Quality Information Shipping Information

#### ♥ VFBGA100

VFBGA100, plastic, very thin fine-pitch ball grid array; 100 balls; 0.5 mm pitch; 6 mm x 6 mm x 0.66 mm body



Buy	Options

## STMP3770XXBJEA2N

935317037557

NOT RECOMMENDED FOR NEW DESIGNS

TRAY-Tray, Bakeable, Multiple in Drypack Min. Package Quantity: 429 Lead Time: 15 weeks

## **Operating Characteristics**

No information available

#### **Environmental Information**

Material Declaration	Pb-	EU	Halogen	RHF	2nd Level	REACH	Weight
	Free	RoHS	Free	Indicator	Interconnect	SVHC	(mg)
Ø STMP3770XXBJEA2N (935317037557)	Yes	Yes	Yes	D	e1	REACH	64.6

## **Quality Information**

Material Declaration	Safe Assure Functional Safety	Moisture Sensitivity Level (MSL)	Peak Package Body Temperature (PPT) (C°)	Maximum Time at Peak Temperatures (s)
		Lead Free Soldering	Lead Free Soldering	Lead Free Soldering
Ø STMP3770XXBJEA2N (935317037557)	No	3	260	40

# **Shipping Information**

Part Number	Harmonized Tariff (US) Disclaimer	Export Control Classification Number (US)
Ø STMP3770XXBJEA2N (935317037557)	854231	5A992

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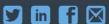
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